

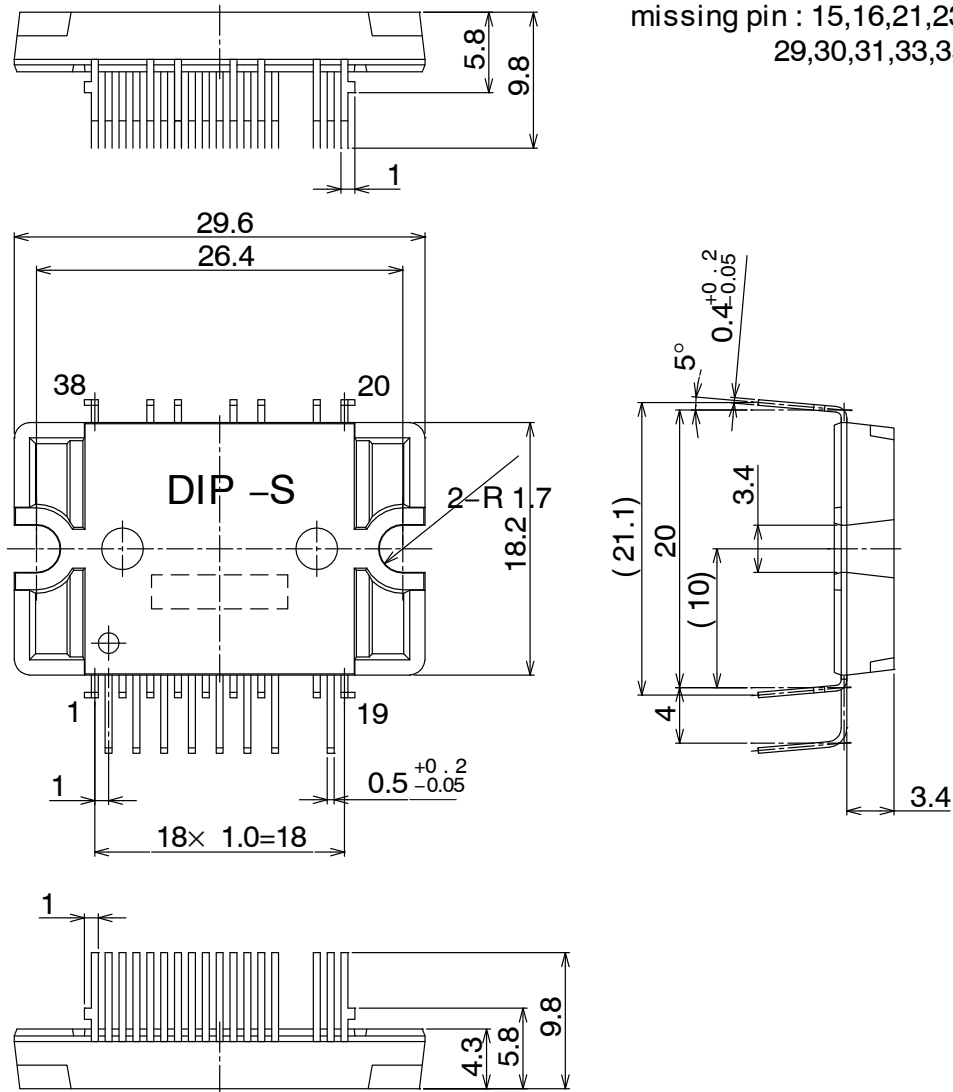
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



HYBRID INTEGRATED MODULE / DIP-S
CASE MODBF
ISSUE 0

DATE 30 JUN 2012



missing pin : 15,16,21,23,24,25,27,
29,30,31,33,35,36,37

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